


| | | |
|----------------------|------------------|--|
| MDOB128032EV-WS | 128 x 32 | OLED Module |
| Specification | | |
| Version: 3 | Date: 10/04/2019 | |
| Revision | | |
| 1 | 19/07/2018 | First release. |
| 2 | 27/11/2018 | Modify Static electricity test Content of Test. |
| 3 | 09/04/2019 | Modify Application recommendations, Absolute Maximum Ratings & Electrical Characteristics. |

| Display Features | |  | Box Quantity | Weight / Display |
|-----------------------|------------------------|---|--------------|------------------|
| Resolution | 128 x 32 | | | |
| Appearance | White on Black | | | |
| Logic Voltage | 3V | | | |
| Interface | SPI | | | |
| Module Size | 32.50 x 20.50 x 2.51mm | | | |
| Operating Temperature | -40°C ~ +80°C | | | |
| Construction | COB | | | |

* - For full design functionality, please use this specification in conjunction with the SSD1306BZ specification. (Provided Separately)

| Display Accessories | |
|---------------------|-------------|
| Part Number | Description |
| | |
| | |
| | |

| Optional Variants | |
|-------------------|---------|
| Appearance | Voltage |
| | |
| | |
| | |



General Specification

The Features is described as follow:

- Module dimension: 32.5 × 20.5 × 2.51 mm
- Active area: 22.384 × 5.584 mm
- Dot Matrix: 128 × 32
- Dot size: 0.152 × 0.152 mm
- Dot pitch: 0.175 × 0.175 mm
- Display Mode : Passive Matrix
- Duty: 1/32 Duty
- Display Color: White
- IC: SSD1306BZ
- Interface: SPI
- Size: 0.91 inch

Interface Pin Function

| No. | Symbol | Function |
|-----|--------|---|
| 1 | SDA | The I2C mode is selected, D2, D1 should be tied together and serve as SDAout, SDAin in application and D0 is the serial clock input, SCL. |
| 2 | SCL | |
| 3 | DC | In I2C mode, this pin acts as DC for slave address selection. When 3-wire serial interface is selected, this pin must be connected to VSS. |
| 4 | RST | This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin HIGH (i.e. connect to VDD) during normal operation. |
| 5 | CS | This pin is the chip select input. (active LOW). |
| 6 | VDD | 2.8 ~ 3.3V Power supply pin for core logic operation. |
| 7 | VIN | 4.8 ~ 5.2V Power supply pin for core logic operation. |
| 8 | GND | This is a ground pin. |



Application recommendations

Application Example of VDD=3.0V :



Application Example of VIN=5.0V :



C1, C2: 1.0uF (1)

Note

(1) The capacitor value is recommended value. Select appropriate value against module application.



Absolute Maximum Ratings

| Parameter | Symbol | Min | Max | Unit | Notes |
|--------------------------|--------|------|-----|------|-------|
| Supply Voltage for Logic | VDD | 1.65 | 3.3 | V | 1,2 |
| Supply Voltage for Logic | VIN | 4.0 | 6.0 | V | 1,2 |
| Operating Temperature | TOP | -40 | +80 | °C | — |
| Storage Temperature | TSTG | -40 | +85 | °C | — |

Note 1: All the above voltages are on the basis of “VSS = 0V”.

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6. “Optics & Electrical Characteristics”. If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

Electrical Characteristics

DC Electrical Characteristics

| Item | Symbol | Condition | Min | Typ | Max | Unit |
|-----------------------------------|--------|-----------|---------|------|---------|------|
| Supply Voltage for Logic (3V) | VDD | — | 2.8 | 3.0 | 3.3 | V |
| Supply Voltage for Logic (5V) | VIN | — | 4.8 | 5.0 | 5.2 | V |
| Input High Volt. | VIH | — | 0.8×VDD | — | VDD | V |
| Input Low Volt. | VIL | — | 0 | — | 0.2×VDD | V |
| Output High Volt. | VOH | — | 0.9×VDD | — | VDD | V |
| Output Low Volt. | VOL | — | 0 | — | 0.1×VDD | V |
| 50% Check Board operating Current | ICC | VDD=3V | — | 13.0 | 26.0 | mA |

Note : VDD or VIN can be selected as Logic Voltage



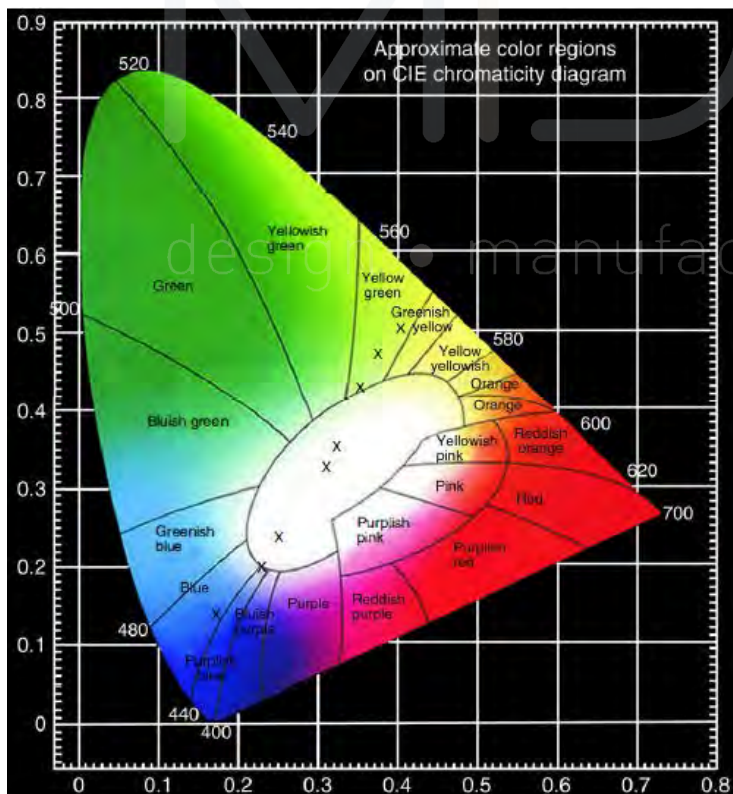
Initial code

```
void Initial_SSD1306BZ(){  
  
    Write_command(0xAE); // Display Off  
  
    Write_command(0xD5); //SET DISPLAY CLOCK  
    Write_command(0x71); //105HZ  
  
    Write_command(0xA8); // Select Multiplex Ratio  
    Write_command(0x1F); // Default => 0x3F (1/64 Duty)    0x1F(1/32 Duty)  
  
    Write_command(0xD3); //Setting Display Offset  
    Write_command(0x00); //00H Reset  
  
    Write_command(0x40); //Set Display Start Line  
    Write_command(0x8D); // Set Charge Pump  
    Write_command(0x14); // Endable Charge Pump  
  
    Write_command(0xA1); //Set Segment Re-Map Default  
  
    Write_command(0xC8); //Set COM Output Scan Direction  
  
    Write_command(0xDA); //Set COM Hardware Configuration  
    Write_command(0x12); //Alternative COM Pin---See IC Spec page 34  
  
    Write_command(0x81); //Set Contrast Control  
    Write_command(0xFF);  
  
    Write_command(0xD9); //Set Pre-Charge period  
    Write_command(0x22);  
  
    Write_command(0xDB); //Set Deselect Vcomh level  
    Write_command(0x40);  
  
    Write_command(0xA4); //Entire Display ON  
  
    Write_command(0xA6); //Set Normal Display  
  
    Write_command(0xAF); // Display ON  
  
}
```



Optical Characteristics

| Item | Symbol | Condition | Min | Typ | Max | Unit |
|--|--------------|-----------|--------|------|------|-------------------|
| View Angle | (V) θ | — | 160 | — | — | deg |
| | (H) ϕ | — | 160 | — | — | deg |
| Contrast Ratio | CR | Dark | 2000:1 | — | — | — |
| Response Time | T rise | — | — | 10 | — | μ s |
| | T fall | — | — | 10 | — | μ s |
| Display with 100% check Board Brightness | | | 120 | 150 | — | cd/m ² |
| CIEx(White) | | (CIE1931) | 0.24 | 0.28 | 0.32 | — |
| CIEy(White) | | (CIE1931) | 0.28 | 0.32 | 0.36 | — |



OLED Lifetime

| ITEM | Conditions | Min | Typ | Remark |
|---------------------|---|------------|-----|--------|
| Operating Life Time | Ta=25°C / Initial 50% check board brightness 100cd/m ² | 20,000 Hrs | - | Note |

Notes:

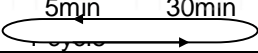
1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
3. Screen saving mode will extend OLED lifetime.

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Reliability

Content of Reliability Test

| Environmental Test | | | |
|--------------------------------------|---|---|---------------------|
| Test Item | Content of Test | Test Condition | Applicable Standard |
| High Temperature storage | Endurance test applying the high storage temperature for a long time. | 85°C 240hrs | — |
| Low Temperature storage | Endurance test applying the low storage temperature for a long time. | -40°C 240hrs | — |
| High Temperature Operation | Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. | 80°C 240hrs | — |
| Low Temperature Operation | Endurance test applying the electric stress under low temperature for a long time. | -40°C 240hrs | — |
| High Temperature/ Humidity Storage | Endurance test applying the high temperature and high humidity storage for a long time. | 60°C,90%RH 240hrs | — |
| High Temperature/ Humidity Operation | Endurance test applying the high temperature and high humidity Operation for a long time. | 60°C,90%RH 120hrs | — |
| Temperature Cycle | Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min  | -40°C /80°C 30 cycles | — |
| Mechanical Test | | | |
| Vibration test | Endurance test applying the vibration during transportation and using. | Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z | — |
| Others | | | |
| Static electricity test | Endurance test applying the electric stress to the finished product housing. | Air Discharge model ±4kv,10 times | — |

*** Supply voltage for OLED system =Operating voltage at 25°C



Test and measurement conditions

1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at $23\pm 5^{\circ}\text{C}$; $55\pm 15\%$ RH.
2. All-pixels-on is used as operation test pattern.
3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

1. The function test is OK.
2. No observable defects.
3. Luminance: $> 50\%$ of initial value.
4. Current consumption: within $\pm 50\%$ of initial value.

APPENDIX:**RESIDUE IMAGE**

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.

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Inspection specification

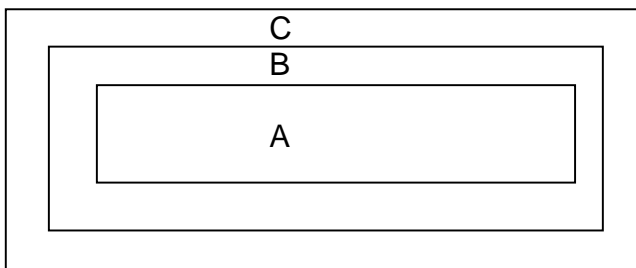
Inspection Standard:

MIL-STD-105E table normal inspection single sample level II.

Definition

- 1 Major defect : The defect that greatly affect the usability of product.
- 2 Minor defect : The other defects, such as cosmetic defects, etc.

Definition of inspection zone:



Zone A: Active Area

Zone B: Viewing Area except Zone A

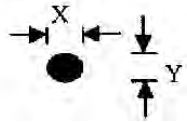
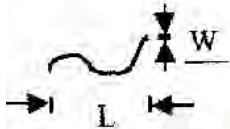
Zone C: Outside Viewing Area

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer`s product.

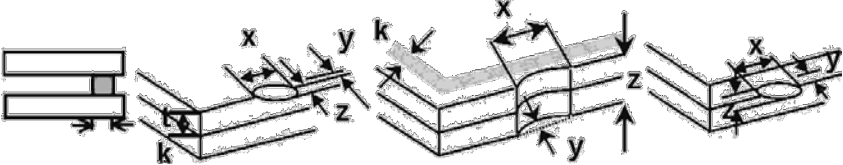
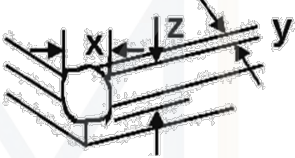
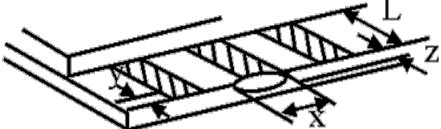
Inspection Methods

- 1 The general inspection : Under fluorescent light illumination: 750~1500 Lux, about 30cm viewing distance, within 45° viewing angle, under 25±5°C.
- 2 The luminance and color coordinate inspection : By SR-3 or BM-7 or the equal equipments, in the dark room, under 25±5°C.

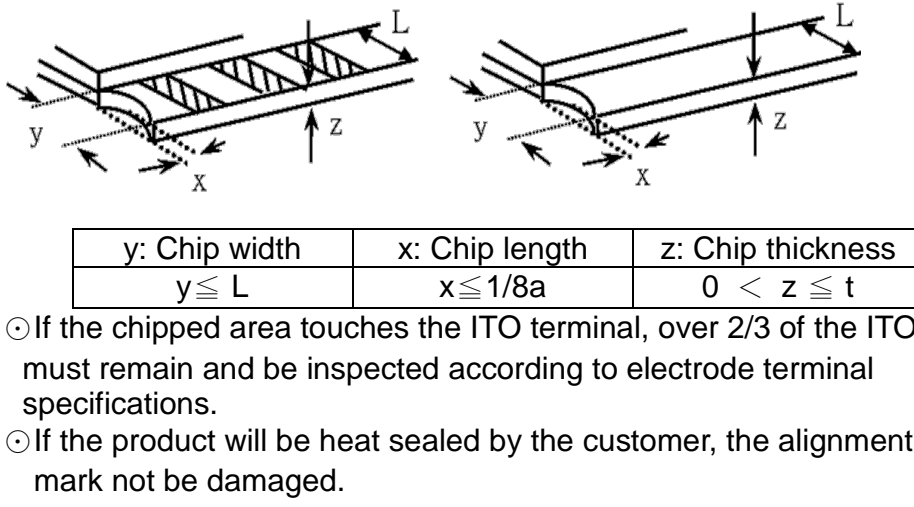
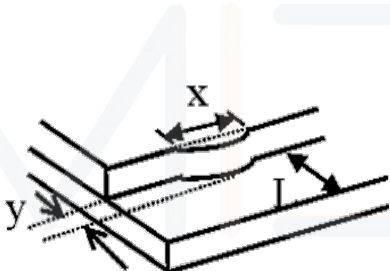
| NO | Item | Criterion | AQL |
|----|---|---|------|
| 01 | Electrical Testing | 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. | 0.65 |
| 02 | Black or white spots on OLED (display only) | 2.1 White and black spots on display $\leq 0.25\text{mm}$, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm. | 2.5 |

| NO | Item | Criterion | AQL | | | | | | | | | | | | | | | | | | | |
|-------------------------|--|---|-------------|----------------|----------------|------------------|-----------------|---------------|-------------------------|-----|--------------|-------------------------|---|------|---------------|----------------------|------|-----------|------------|---------------|-----|-----|
| 03 | OLED black spots, white spots, contamination (non-display) | <p>3.1 Round type : As following drawing $\Phi = (x + y) / 2$</p>  <table border="1"> <thead> <tr> <th>SIZE</th> <th>Acceptable QTY</th> <th>Zone</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.10$</td> <td>Accept no dense</td> <td>A+ B,</td> </tr> <tr> <td>$0.10 < \Phi \leq 0.20$</td> <td>2</td> <td>A+ B</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.25$</td> <td>1</td> <td>A+ B</td> </tr> <tr> <td>$0.25 < \Phi$</td> <td>0</td> <td>A+ B</td> </tr> </tbody> </table> | SIZE | Acceptable QTY | Zone | $\Phi \leq 0.10$ | Accept no dense | A+ B, | $0.10 < \Phi \leq 0.20$ | 2 | A+ B | $0.20 < \Phi \leq 0.25$ | 1 | A+ B | $0.25 < \Phi$ | 0 | A+ B | 2.5 | | | | |
| | SIZE | Acceptable QTY | Zone | | | | | | | | | | | | | | | | | | | |
| $\Phi \leq 0.10$ | Accept no dense | A+ B, | | | | | | | | | | | | | | | | | | | | |
| $0.10 < \Phi \leq 0.20$ | 2 | A+ B | | | | | | | | | | | | | | | | | | | | |
| $0.20 < \Phi \leq 0.25$ | 1 | A+ B | | | | | | | | | | | | | | | | | | | | |
| $0.25 < \Phi$ | 0 | A+ B | | | | | | | | | | | | | | | | | | | | |
| | | <p>3.2 Line type : (As following drawing)</p>  <table border="1"> <thead> <tr> <th>Length</th> <th>Width</th> <th>Acceptable QTY</th> <th>Zone</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> <td>A+B</td> </tr> <tr> <td>$L \leq 3.0$</td> <td>$0.02 < W \leq 0.03$</td> <td rowspan="2">2</td> <td>A+B</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.05$</td> <td>A+B</td> </tr> <tr> <td>---</td> <td>$0.05 < W$</td> <td>As round type</td> <td></td> </tr> </tbody> </table> | Length | Width | Acceptable QTY | Zone | --- | $W \leq 0.02$ | Accept no dense | A+B | $L \leq 3.0$ | $0.02 < W \leq 0.03$ | 2 | A+B | $L \leq 2.5$ | $0.03 < W \leq 0.05$ | A+B | --- | $0.05 < W$ | As round type | | 2.5 |
| Length | Width | Acceptable QTY | Zone | | | | | | | | | | | | | | | | | | | |
| --- | $W \leq 0.02$ | Accept no dense | A+B | | | | | | | | | | | | | | | | | | | |
| $L \leq 3.0$ | $0.02 < W \leq 0.03$ | 2 | A+B | | | | | | | | | | | | | | | | | | | |
| $L \leq 2.5$ | $0.03 < W \leq 0.05$ | | A+B | | | | | | | | | | | | | | | | | | | |
| --- | $0.05 < W$ | As round type | | | | | | | | | | | | | | | | | | | | |
| 04 | Polarizer bubbles | <p>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.</p> <table border="1"> <thead> <tr> <th>Size Φ</th> <th>Acceptable QTY</th> <th>Zone</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.20$</td> <td>Accept no dense</td> <td>A+B</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.50$</td> <td>3</td> <td>A+B</td> </tr> <tr> <td>$0.50 < \Phi \leq 1.00$</td> <td>2</td> <td>A+B</td> </tr> <tr> <td>$1.00 < \Phi$</td> <td>0</td> <td>A+B</td> </tr> <tr> <td>Total QTY</td> <td>3</td> <td></td> </tr> </tbody> </table> | Size Φ | Acceptable QTY | Zone | $\Phi \leq 0.20$ | Accept no dense | A+B | $0.20 < \Phi \leq 0.50$ | 3 | A+B | $0.50 < \Phi \leq 1.00$ | 2 | A+B | $1.00 < \Phi$ | 0 | A+B | Total QTY | 3 | | 2.5 | |
| Size Φ | Acceptable QTY | Zone | | | | | | | | | | | | | | | | | | | | |
| $\Phi \leq 0.20$ | Accept no dense | A+B | | | | | | | | | | | | | | | | | | | | |
| $0.20 < \Phi \leq 0.50$ | 3 | A+B | | | | | | | | | | | | | | | | | | | | |
| $0.50 < \Phi \leq 1.00$ | 2 | A+B | | | | | | | | | | | | | | | | | | | | |
| $1.00 < \Phi$ | 0 | A+B | | | | | | | | | | | | | | | | | | | | |
| Total QTY | 3 | | | | | | | | | | | | | | | | | | | | | |
| 05 | Scratches | Follow NO.3 OLED black spots, white spots, contamination. | | | | | | | | | | | | | | | | | | | | |



| NO | Item | Criterion | AQL | | | | | | | | | |
|-----------------------|--|---|-------------------|----------------|-------------------|-----------------------|-----------------------|--------------------|--------------------|-----------------|---------------|-----|
| 06 | Chipped glass | <p>Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="427 707 1315 831"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </table> <p>⊙ If there are 2 or more chips, x is total length of each chip.</p> | z: Chip thickness | y: Chip width | x: Chip length | $Z \leq 1/2t$ | Not over viewing area | $x \leq 1/8a$ | $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 1/8a$ | 2.5 |
| | z: Chip thickness | y: Chip width | x: Chip length | | | | | | | | | |
| $Z \leq 1/2t$ | Not over viewing area | $x \leq 1/8a$ | | | | | | | | | | |
| $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 1/8a$ | | | | | | | | | | |
| | <p>6.1.2 Corner crack:</p>  <table border="1" data-bbox="427 1149 1335 1272"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </table> <p>⊙ If there are 2 or more chips, x is the total length of each chip.</p> | z: Chip thickness | y: Chip width | x: Chip length | $Z \leq 1/2t$ | Not over viewing area | $x \leq 1/8a$ | $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 1/8a$ | 2.5 | |
| z: Chip thickness | y: Chip width | x: Chip length | | | | | | | | | | |
| $Z \leq 1/2t$ | Not over viewing area | $x \leq 1/8a$ | | | | | | | | | | |
| $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 1/8a$ | | | | | | | | | | |
| | Glass crack | <p>Symbols : x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad :</p>  <table border="1" data-bbox="427 1704 1315 1787"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> | y: Chip width | x: Chip length | z: Chip thickness | $y \leq 0.5\text{mm}$ | $x \leq 1/8a$ | $0 < z \leq t$ | 2.5 | | | |
| y: Chip width | x: Chip length | z: Chip thickness | | | | | | | | | | |
| $y \leq 0.5\text{mm}$ | $x \leq 1/8a$ | $0 < z \leq t$ | | | | | | | | | | |

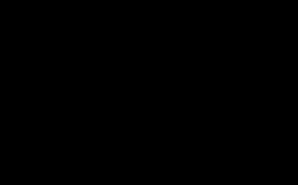
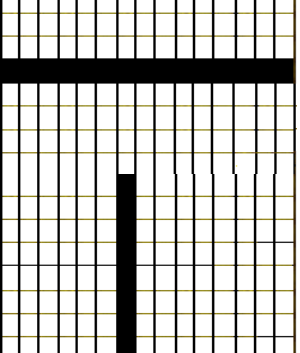
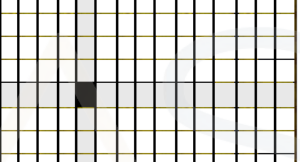
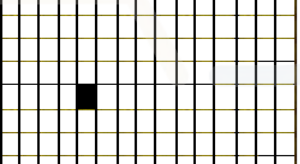
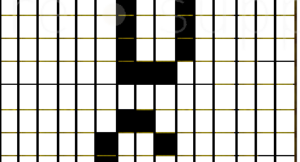
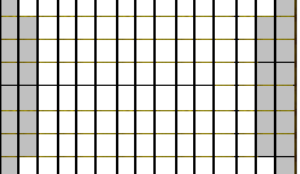


| NO | Item | Criterion | AQL | | | | | | | | | | |
|---------------|--------------------|---|---------------------|----------------|-------------------|------------|---------------|----------------|----------|-----------|---------------|------------|-----|
| 06 | Glass crack | <p>6.2.2 Non-conductive portion:</p>  <table border="1" data-bbox="496 573 1353 651"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <ul style="list-style-type: none"> ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. <p>6.2.3 Substrate protuberance and internal crack.</p>  <table border="1" data-bbox="826 927 1318 1005"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$x \leq a$</td> </tr> </table> | y: Chip width | x: Chip length | z: Chip thickness | $y \leq L$ | $x \leq 1/8a$ | $0 < z \leq t$ | y: width | x: length | $y \leq 1/3L$ | $x \leq a$ | 2.5 |
| y: Chip width | x: Chip length | z: Chip thickness | | | | | | | | | | | |
| $y \leq L$ | $x \leq 1/8a$ | $0 < z \leq t$ | | | | | | | | | | | |
| y: width | x: length | | | | | | | | | | | | |
| $y \leq 1/3L$ | $x \leq a$ | | | | | | | | | | | | |
| 07 | Cracked glass | The OLED with extensive crack is not acceptable. | 2.5 | | | | | | | | | | |
| 08 | Backlight elements | <p>8.1 Illumination source flickers when lit.</p> <p>8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards.</p> <p>8.3 Backlight doesn't light or color wrong.</p> | 0.65 2.5 0.65 | | | | | | | | | | |
| 09 | Bezel | <p>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</p> <p>9.2 Bezel must comply with job specifications.</p> | 2.5 0.65 | | | | | | | | | | |



| NO | Item | Criterion | AQL |
|----|--------------------|--|------|
| 10 | PCB , COB | 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. | 2.5 |
| | | 10.2 COB seal surface may not have pinholes through to the IC. | 2.5 |
| | | 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. | 0.65 |
| | | 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. | 2.5 |
| | | 10.5 No oxidation or contamination PCB terminals. | 2.5 |
| | | 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. | 0.65 |
| | | 10.7 The jumper on the PCB should conform to the product characteristic chart. | 0.65 |
| | | 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. | 2.5 |
| 11 | Soldering | 11.1 No un-melted solder paste may be present on the PCB. | 2.5 |
| | | 11.2 No cold solder joints, missing solder connections, oxidation or icicle. | 2.5 |
| | | 11.3 No residue or solder balls on PCB. | 2.5 |
| | | 11.4 No short circuits in components on PCB. | 0.65 |
| 12 | General appearance | 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. | 2.5 |
| | | 12.2 No cracks on interface pin (OLB) of TCP. | 0.65 |
| | | 12.3 No contamination, solder residue or solder balls on product. | 2.5 |
| | | 12.4 The IC on the TCP may not be damaged, circuits. | 2.5 |
| | | 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. | 2.5 |
| | | 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. | 2.5 |
| | | 12.7 Sealant on top of the ITO circuit has not hardened. | 2.5 |
| | | 12.8 Pin type must match type in specification sheet. | 0.65 |
| | | 12.9 OLED pin loose or missing pins. | 0.65 |
| | | 12.10 Product packaging must the same as specified on packaging specification sheet. | 0.65 |
| | | 12.11 Product dimension and structure must conform to product specification sheet. | 0.65 |



| Check Item | Classification | Criteria | | | | | | |
|--|----------------|--|---|--------|---|------------|---|-------------|
| No Display | Major |  | | | | | | |
| Missing Line | Major |  | | | | | | |
| Pixel Short | Major |  | | | | | | |
| Darker Short | Major |  | | | | | | |
| Wrong Display | Major |  | | | | | | |
| Un-uniform $B/A \times 100\% < 70\%$ $A/C \times 100\% < 70\%$ | Major |  <div data-bbox="991 1630 1286 1839"> <table border="1"> <tr> <td data-bbox="991 1641 1114 1697">A</td> <td data-bbox="1114 1641 1209 1697">Normal</td> </tr> <tr> <td data-bbox="991 1697 1114 1753">B</td> <td data-bbox="1114 1697 1209 1753">Dark Pixel</td> </tr> <tr> <td data-bbox="991 1753 1114 1809">C</td> <td data-bbox="1114 1753 1209 1809">Light Pixel</td> </tr> </table> </div> | A | Normal | B | Dark Pixel | C | Light Pixel |
| A | Normal | | | | | | | |
| B | Dark Pixel | | | | | | | |
| C | Light Pixel | | | | | | | |



Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) MIDAS has the right to change the passive components, including R2 and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) MIDAS have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, MIDAS have the right to modify the version.)

Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.

* Scotch Mending Tape No. 810 or an equivalent

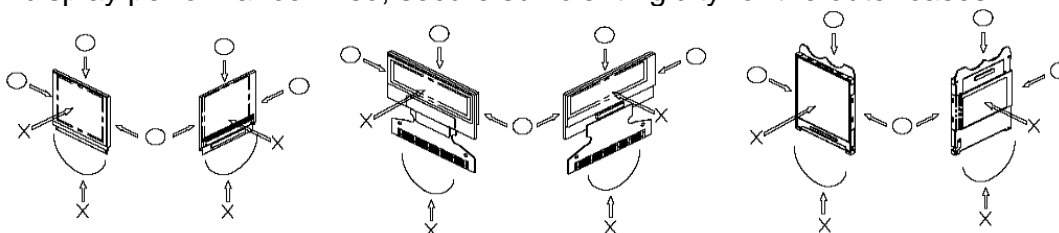
Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent
Also, pay attention that the following liquid and solvent may spoil the polarizer:

* Water

* Ketone

* Aromatic Solvents

- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
 - * Be sure to make human body grounding when handling OLED display modules.
 - * Be sure to ground tools to use or assembly such as soldering irons.
 - * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
 - * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from MIDAS. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.)
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.

